

WHAT IS CLAIMED IS:

1. A circuit board comprising:

a terminal portion connected with an external terminal
formed in an external circuit, said terminal portion provided
5 with a nickel plating layer and a soldering bump;

wherein a thickness of said nickel plating layer is
within a range of 1.0 to 4.0 μm .

2. A circuit board according to Claim 1, wherein said
10 soldering bump contains tin and at least one of silver and
copper.

3. A circuit board according to Claim 1, wherein said
soldering bump contains tin, silver and copper.

4. A circuit board according to Claim 1, wherein said
circuit board is a circuit-provided suspension substrate.

5. A connection structure for connecting a terminal portion.
20 of a circuit board with an external terminal formed in an
external circuit, wherein said terminal portion is provided
with a nickel plating layer and a soldering bump provided on
said terminal portion and a thickness of said nickel plating
layer is within a range of 1.0 to 4.0 μm .